



Material Composition Declaration

EPC2307

Company Name	Efficient Power Conversion (EPC)	Issue Date:	2024/11/1
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	30.3 mg	Type of Product:	eGaN FET in FCQFN package

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	4.9489	16.3373	17.2447	163373
	Silicon oxide	7631-86-9	0.0342	0.1128		1128
	Silicon nitride	12033-89-5	0.0238	0.0786		786
	Gallium nitride	25617-97-4	0.0501	0.1655		1655
	Aluminum	7429-90-5	0.0643	0.2123		2123
	Aluminum nitride	24304-00-5	0.0118	0.0389		389
	Titanium	7440-32-6	0.0020	0.0065		65
	Titanium nitride	25583-20-4	0.0131	0.0432		432
	Copper	7440-50-8	0.0011	0.0035		35
	Tungsten	7440-33-7	0.0060	0.0197		197
	Polyimide		0.0686	0.2264	2264	
Under Bump Metal	Titanium	7440-32-6	0.0005	0.0016	0.0175	16
	Copper	7440-50-8	0.0048	0.0159		159
Solder Bump	Copper	7440-50-8	0.4057	1.3394	1.8302	13394
	Nickel	7440-02-0	0.0288	0.0951		951
	Tin	7440-31-5	0.1177	0.3885		3885
	Silver	7440-22-4	0.0022	0.0071		71
Package	Copper	7440-50-8	11.7262	38.7103	80.9076	387103
	Iron	7439-89-6	0.3007	0.9926		9926
	Mold Compound		11.7959	38.9403		389403
	Tin	7440-31-5	0.6859	2.2644		22644
Sum in total:			30.2922	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.